FEATURES

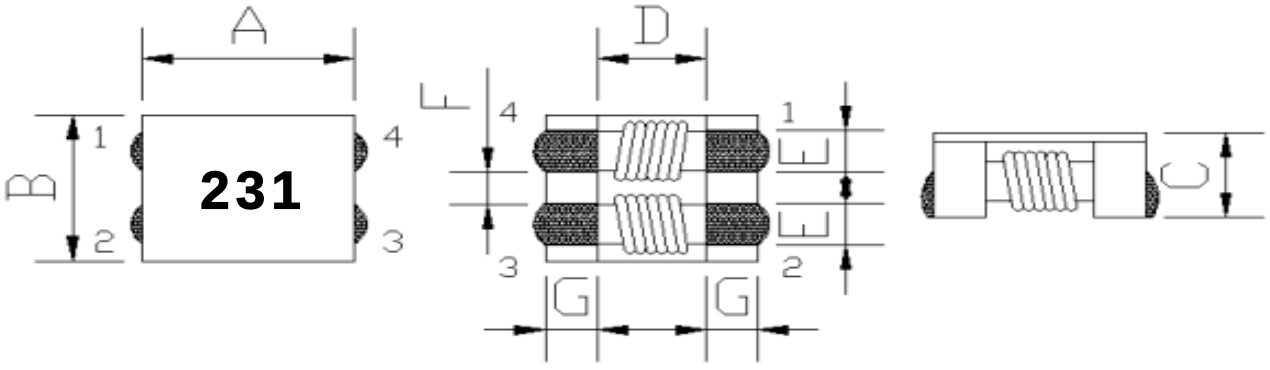
- Surface mountable (multiple case sizes), high current common mode choke for DC power line
- Base terminals are treated, allows for easy mounting on PCB
- Paired wire coil for high stability
- Optimized for transmission of high quality signals
- Operating temperature: -40 °C to +125 °C
- Rated Current: Based on temp. rise; ΔT: 40 °C, typical
- Material categorization: For definitions of compliance please see

APPLICATIONS

- LAN's, telephones, personal computers
- CD-ROM drives, electronic games
- Other electronic devices

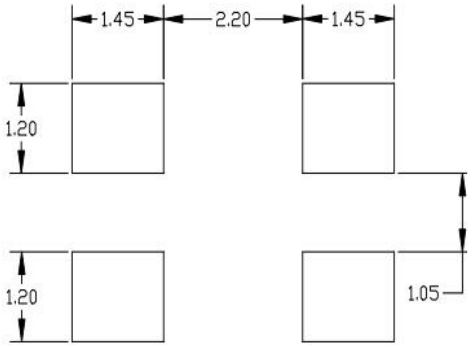
STANDARD ELECTRICAL SPECIFICATIONS					
PART NUMBER	COMMON MODE IMPEDANCE AT 100 MHz (Ω)	RATED VOLTAGE MAX. (V_{DC})	RATED CURRENT MAX. (mA)	DC RESISTANCE MAX. (Ω)	INSULATION RESISTANCE MIN. (MΩ)
CMF2E231WIT	230±25%	50	1500	0.05	10
CMF2E301WIT	300±25%	50	1500	0.05	10
CMF2E401WIT	400±25%	50	1400	0.055	10
CMF2E421WIT	420±25%	50	1400	0.055	10
CMF2E501WIT	500±25%	50	1300	0.06	10
CMF2E701WIT	700±25%	50	1300	0.07	10
CMF2E901WIT	900±25%	50	1200	0.08	10
CMF2E102WIT	1000±25%	50	1200	0.085	10
CMF2E142WIT	1400±25%	50	1100	0.1	10

MECHANICAL DIMENSION:

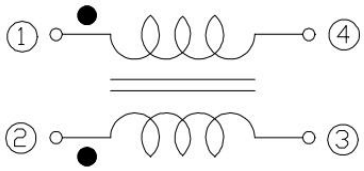


NOTE：Dimensions in mm							
PRODUCT NO	A	B	C	D	E	F	G
CMF2E	4.7 ± 0.5	4.5 ± 0.5	2.0 MAX	2.7 Typ	0.75 Typ	1.25 Typ	1.0 Typ

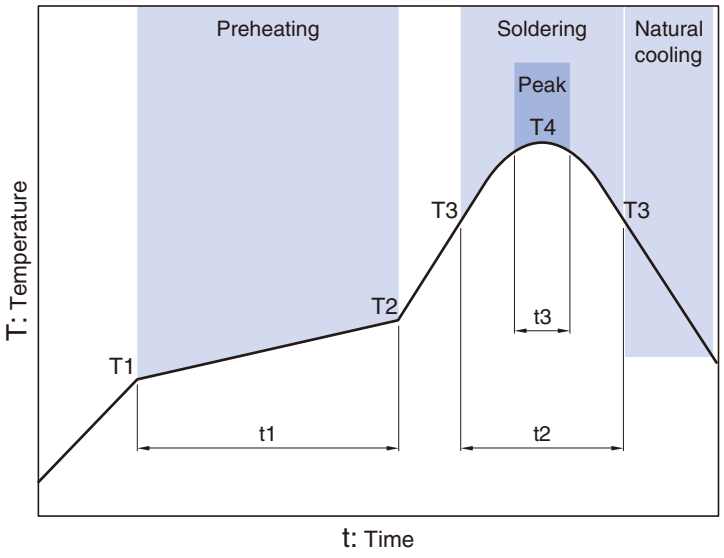
LAND PATTERN(Unit: mm):



SCHEMATIC:



RECOMMENDED REFLOW PROFILE



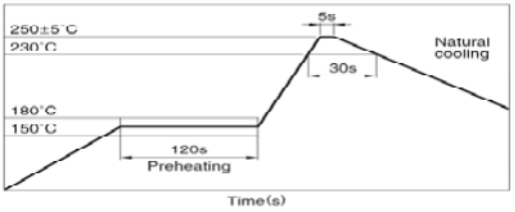
Preheating			Soldering		Peak	
Temp.		Time	Temp.	Time	Temp.	Time
T1	T2	t1	T3	t2	T4	t3
150°C	180°C	60 to 120s	230°C	25 to 35s	250°C	5s

RELIABLITY TEST METHOD

- **ELECTRIC**

NO.	Test items	Standard	Experiment Method
1	Temperature characteristics	ΔL/L 20°C ≤ ±10%	The test should be done after the sample has stabilized in the ring The temperature of the product is -40 to +125 °C, and the L (ΔL) value of the product is the same as the original L value. Suitable for normal temperature and humidity should be ΔL / L 20 ° C ≤ ± 10 %.
2	Load test	The product must not have any damage, such as smoke or sparks	1.2 times the rated current, the time is 5 minutes

6.2 **ENVIRONMENTAL CHARACTERISTICS**

<table>
<tr><th>NO.</th><th>Test items</th><th>Standard</th><th>Experiment Method</th></tr>
<tr><td>1</td><td>Reflow soldering</td><td>Do not have any damage or problems</td><td>Reflow of temperature distribution
Before the heat: 150-180 °C, Times 60 to 120sec
Peak temperature: 250 ± 5 °C, Times 5 sec
Hold temperature: 230 ± 5 °C, Times 30 ± 5 sec

</td></tr>
<tr><td>2</td><td>Solderability</td><td>Welding area of more than 90%</td><td>The solder surface is immersed in flux and then immersed in a furnace at 235 ± 5 °C for 5 seconds</td></tr>
<tr><td>3</td><td>Low temperature storage</td><td>ΔL / L0 ≤ ± 10%, there should be no mechanical damage</td><td>The sample should be left for 96 ± 4 hours at a temperature of -40 ± 3 °C and returned to the normal temperature range of 1 hour after completion of the test.) 90-95%.</td></tr>
<tr><td>4</td><td>High temperature storage</td><td>ΔL / L0 ≤ ± 10%, there should be no mechanical damage</td><td>The sample should be left for 96 ± 4 hours at a temperature of 125 ± 3 °C. The test should be carried out after returning to normal temperature range for 1 hour.</td></tr>
<tr><td>5</td><td>Constant hot and humid</td><td>ΔL / L0 ≤ ± 10%, there should be no mechanical damage.</td><td>Samples should be left for 96 ± 4 hours at 60 ± 2 °C and 90 °C to 90% humidity (RH). The test is resumed after 1 hour in the normal temperature range.</td></tr>
<tr><td>6</td><td>Temperature cycle</td><td>1, no visible mechanical damage.
2, the value of change is less than 10%.
3, the resistance value of less than 5%</td><td>In the -25 °C to +85 °C between the respective keep 15min, transit time ≤1min, the number of cycles 5 times,
recovery time: 24h test finished (recovery time at least 4h)</td></tr>
<tr><td>7</td><td>vibration</td><td>ΔL / L0 ≤ ± 10%
There should be no mechanical damage</td><td>The sample should be soldered to the printed circuit board
When the vibration has an amplitude and 1.5 mm
Frequency from 10-55Hz / 1 minute, repeated should be applied to three directions (X, Y, Z) for 2 hours, a total of 6 hours</td></tr>
<tr><td>8</td><td>Impact resistance (MIL-STD-202G Method 213B)</td><td>Change in inductance: within ± 10%
DC resistance change: ± 10% within the appearance of no obvious abnormalities, should not have mechanical damage.</td><td>The test sample shall be soldered to the test substrate by reflow soldering.
Then, follow the following test conditions.
<table>
<tr><th>Pulse</th><th>Half sine shock</th></tr>
<tr><td>Acceleration</td><td>980 m/s^2(100g)</td></tr>
<tr><td>Nominal pulse duration</td><td>6 ms</td></tr>
<tr><td>Speed change</td><td>3.75 m/s</td></tr>
</table>
Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</td></tr>
</table>

<table>
<tr>
<td>9</td>
<td>Thermal shock
(MIL-STD-202G
Method 107G)</td>
<td>Change in inductance: within ± 10%
DC resistance change: ± 10% within the appearance of no obvious abnormalities, should not have mechanical damage.</td>
<td>The test sample shall be soldered to the test substrate by reflow soldering. Test sample according to the specified time
Are placed at a specific temperature, as shown in the table below, from step 1 to step 4.
<table>
<tr><th colspan="3">1 cycle condition</th></tr>
<tr><th>Step</th><th>Temperature（°C）</th><th>Time（minute）</th></tr>
<tr><td>1</td><td>-55±3</td><td>30±3</td></tr>
<tr><td>2</td><td>Room temperature</td><td>3 or less</td></tr>
<tr><td>3</td><td>-125±3</td><td>30±3</td></tr>
<tr><td>4</td><td>Room temperature</td><td>3 or less</td></tr>
</table>
Recovery: 2 hours of recovery in standard condition
and subsequent testing within 48 hours.</td>
</tr>
<tr>
<td>10</td>
<td>Wet heat resistance
(MIL-STD-202G
Method 106G)</td>
<td>Change in inductance: within ± 10%
DC resistance change: ± 10% within the appearance of no obvious abnormalities, should not have mechanical damage.</td>
<td>The test sample shall be soldered to the test substrate by reflow soldering.
Test samples must be placed in a constant temperature and humidity box, according to the table specified temperature and humidity, do not pass the current test.
<table>
<tr><td>Temperature</td><td>65±2°C</td></tr>
<tr><td>Humidity</td><td>90%±10%RH</td></tr>
<tr><td>Time</td><td>500±24 hours</td></tr>
</table>
Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</td>
</tr>
<tr>
<td>11</td>
<td>Low temperature life
(IEC68-2-1Ad)</td>
<td>Change in inductance: within ± 10%
DC resistance change: ± 10% within the appearance of no obvious abnormalities, should not have mechanical damage.</td>
<td>The test sample shall be soldered to the test substrate by reflow soldering.
The test sample should then be placed in the test conditions as shown in the table below.
<table>
<tr><td>Temperature</td><td>-40±3°C</td></tr>
<tr><td>Time</td><td>500±24 hours</td></tr>
</table>
Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</td>
</tr>
<tr>
<td>12</td>
<td>Low temperature load life
(IEC68-2-1Ad)</td>
<td>Change in inductance: within ± 10%
DC resistance change: ± 10% within the appearance of no obvious abnormalities, should not have mechanical damage.</td>
<td>The test sample shall be soldered to the test substrate by reflow soldering. The
<table>
<tr><td>Temperature</td><td>-55±2°C</td></tr>
<tr><td>Plus load current</td><td>Rated current</td></tr>
<tr><td>Time</td><td>500±24 hours</td></tr>
<tr><td>Hourly power time</td><td>3/4 power 1/4 power off</td></tr>
</table>
Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</td>
</tr>
<tr>
<td>13</td>
<td>Damp heat load
(MIL-STD-202G
Method 108A)</td>
<td>Change in inductance: within ± 10%
DC resistance change: ± 10% within the appearance of no obvious abnormalities, should not have mechanical damage.</td>
<td>The test sample shall be soldered to the test substrate by reflow soldering.
Test samples shall be placed in a constant temperature and humidity box, according to the table specified in the temperature and humidity under the continuous access to the rated current for testing.
<table>
<tr><td>Temperature</td><td>60±2°C</td></tr>
<tr><td>Humidity</td><td>90~95%RH</td></tr>
<tr><td>Time</td><td>500±24 hours</td></tr>
</table>
Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</td>
</tr>
</table>

<table>
<tr><td>14</td><td>High temperature life test (IEC68-2-2Ba)</td><td>Change in inductance: within ± 10%
DC resistance change: ± 10% within the appearance of no obvious abnormalities, should not have mechanical damage.</td><td>The test sample shall be soldered to the test substrate by reflow soldering.
The test sample shall be placed in a constant temperature and humidity tank and the current shall not be supplied at the temperature specified in the table.
<table><tr><td>Temperature</td><td>125±3°C</td></tr><tr><td>Time</td><td>500±24 hours</td></tr></table>
Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</td></tr>
<tr><td>15</td><td>High temperature load life test (MIL-STD-202G Method 108A)</td><td>Change in inductance: within ± 10%
DC resistance change: ± 10% within the appearance of no obvious abnormalities, should not have mechanical damage.</td><td>The test sample shall be soldered to the test substrate by reflow soldering. The
<table><tr><td>Temperature</td><td>85±2°C</td></tr><tr><td>Plus load current</td><td>Rated current</td></tr><tr><td>Time</td><td>2000±24 hours</td></tr><tr><td>Hourly power time</td><td>3/4 power 1/4 power off</td></tr></table>
Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</td></tr>
</table>